



Product/Process Change Notice - PCN 18_0036 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: ADGM1304 Die Revision, Datasheet Change and Assembly Site transfer for Select side by side LFCSP in ASE Korea (AEK)

Publication Date: 02-Oct-2019

Effectivity Date: 04-Jan-2020 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change:

All layer re-design of the driver IC used in the ADGM1304.

This re-design has widened supply voltage range. There is minor pin out configuration changes of the ADGM1304 part due to added SPI functionality, while still supporting existing applications. See attachment for datasheet change details.

Assembly site for select side by side LFCSP is moving from Amkor, Philippines (AP3) to existing qualified site ASE, Korea (AEK). Existing qualified BOM sets in AEK will be used

Reason For Change:

Reason for re-design: Improved part performance, added SPI functionality and screening ability.

Reason for assembly site transfer: Amkor Philippines (AP3) issued discontinuance notice to ADI on the manufacture of select LFCSP side by side package (ADGM1304).

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, materials, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

This redesign and assembly site transfer will not affect the form, fit, quality or reliability of the ADGM1304 part. Qualified material set in AEK will be used.

Product Identification *(this section will describe how to identify the changed material)*

Changeover Material Date code is 1938

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_18_0036_Rev_-_Supporting Qualification Data ADGM1304 PCN.pdf

Attachment 2: Type: Qualification Results Summary

ADI_PCN_18_0036_Rev_-_000895_Qual Results Summary for Side-by-Side LFCSP at AEK.pdf

Attachment 3: Type: Datasheet Specification Comparison

Attachment 4: Type: Other

ADI_PCN_18_0036_Rev_-_BOM Set Comparison Amkor and ASE.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:

PCN_Americas@analog.com

Europe:

PCN_Europe@analog.com

Japan:

PCN_Japan@analog.com

Rest of Asia:

PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (2)

ADGM1304 / ADGM1304JCPZ-R2

ADGM1304 / ADGM1304JCPZ-RL7

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	02-Oct-2019	04-Jan-2020	Initial Release

Analog Devices, Inc.

DocId:4371 Parent DocId:4099 Layout Rev:7